Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model **[List multiple models if applicable.]**
Name / Model #1 Blade PC Enclosure G2
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	**Notes**	**Quantity of items included in product**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
screwdriver	T15
screwdriver	451N
screwdriver	Cr-V 5mm
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Blade Card(BC)

   1) Remove the Blade cards:

      a) Press the Blade card handle down. (see Figure 1 as below)

      b) Catch the handle and pull out the blade card(see Figure 2 as below)

   2) Disassembly the Blade card

      a) Remove the screws on Heat sink and pick up the heat sink from the blade card (see Figure 3&4 as below)

      b) Push the clip back to the horizontal direction that holds the battery in place, and then remove the battery from the blade card (see Figure 5 as below)

      c) Remove the CPU from the blade card (see Figure 6&7 as below)

      d) Pull the metal handle of the RAM slot to two side,and then take up the RAM from the blade card (seeFigure8&9 as below)

      e) Remove the HDD from the BC(see Figure 10&11 as below)

      f) Remove the power light(see Figure 12 as below)

2. PSU

   1) Remove the power supply from the unit (see Figure 13&14 as below),

   2) Remove the side screws holding the enclosure of the power supply (see Figure 15&16 as below),

   3) Remove the top screws holding the enclosure of the power supply (see Figure 17&18 as below)

   4) Remove the holding metal for the inside PSU (see Figure 19 as below)

   5) Remove the screws of the power supply (see Figure 20&21 as below)

   6) Remove the screws of the PCA (see Figure 22 as below)

   7) Remove the fan ((see Figure 23 as below)

8) Remove the Electrolytic Capacitors:
    a) Using Soldering Iron, heat the solder of Electrolytic Capacitors.(see Figure 24&25 below)
    b) Remove the Electrolytic Capacitors.

3. BACKPLANE
    1) Open the top enclosure of the unit (see Figure 26 as below),
    2) Pull the handle in the two side slot of the power supply (see Figure 27 as below)
    3) Remove the backplane by hands (see Figure 28 as below)
    4) Remove the top PCA on the backplane (see Figure 29&30 as below)
    5) Remove the backplane PCA
        a) Using Soldering Iron, heat the solder of Electrolytic Capacitors.(see Figure 31 below)
        b) Remove the screws on the backplane PCA(see Figure 32 as below)
        c) Remove the backplane PCA from the base matel (see Figure 33 as below)
4. FAN Controller
    1) Cut off the fan connector with the midplane (see Figure 34 as below),
    2) Push down the button at the back of unit (see Figure 35 as below),
    3) Pull out the Fan controller from the unit (see Figure 36 as below)
    4) Push down the second button and pull out the fan controller from the unit (see Figure 37 as below),
    5) Remove the screw inside the fan cotroller (see Figure 38 as below),
    6) Push the handles to the centre and then pull out the four fan (see Figure 39 as below),
5. MIDPLANE
    1) Remove two side screws of the midplane (see Figure 40 as below),
    2) Pull out the midplane from the unit (see Figure 41 as below),
    3) Remove the screws on the two side of the midplane(see Figure 42&43 as below))

6.
7.
8.
9.
10.
11.
12.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

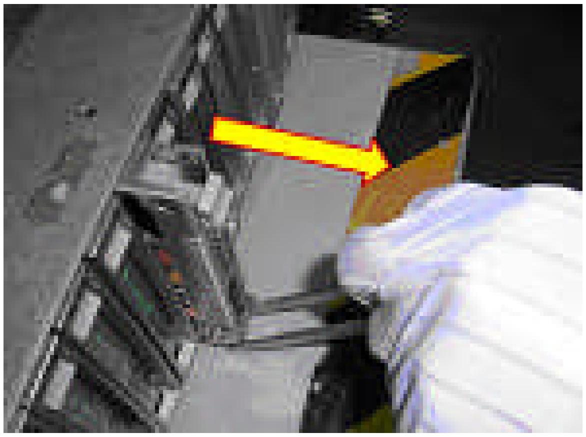
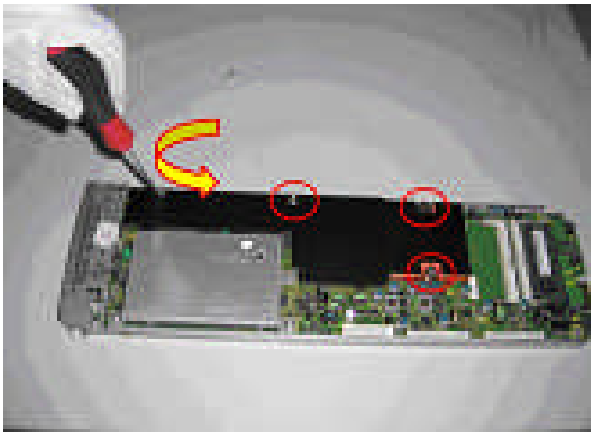
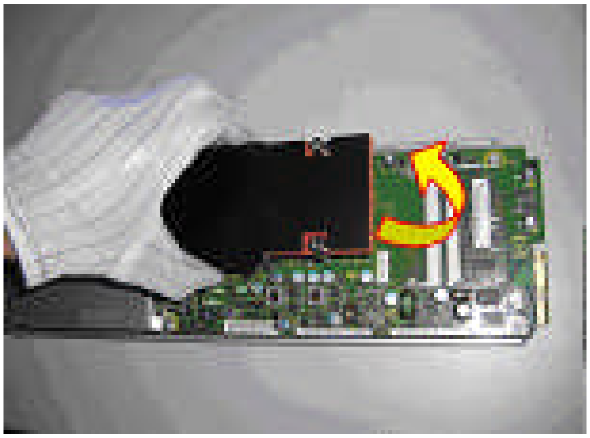
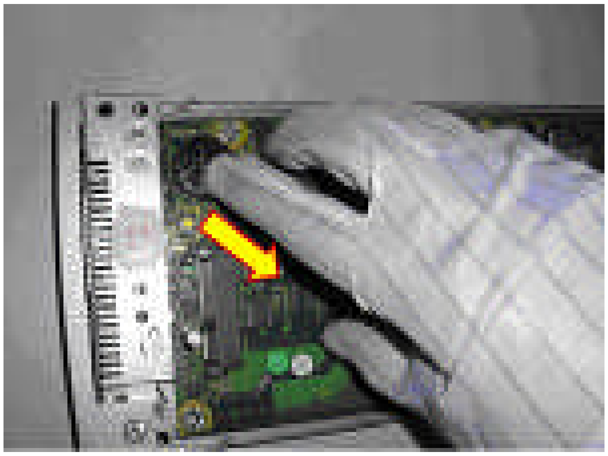
Figure 1 Press the Blade card handle down 	Figure 2 pull out the blade card 
Figure 3 Remove the screws of the heat sink 	Figure 4 Remove the heat sink from the BC 
Figure 5 Remove the battery 	Figure 6 Remove the CPU 

Figure 7 Take up the CPU from the BC

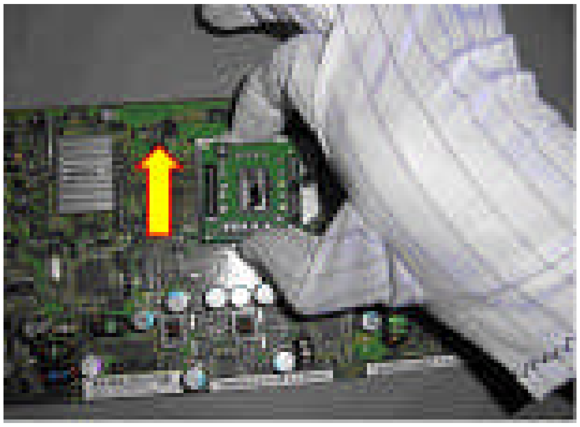


Figure 8 Pull the metal to two side

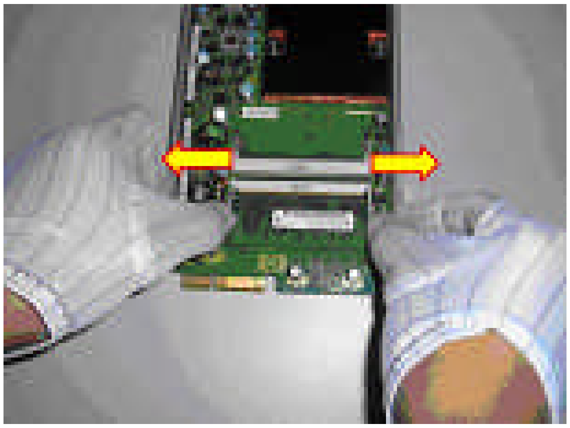


Figure 9 Take up the RAM

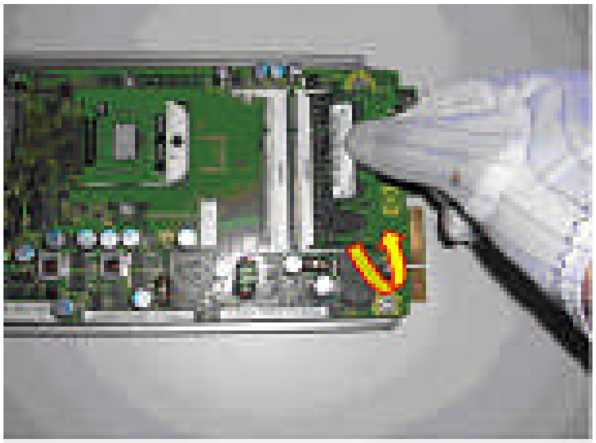


Figure 10 Remove the screws that holding the HDD

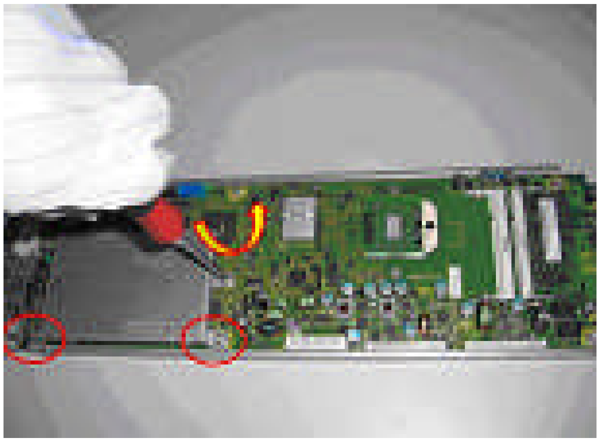


Figure 11 Pull out the HDD

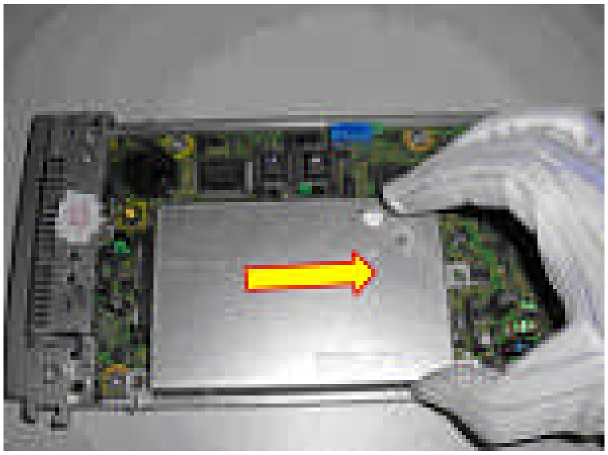


Figure 12 Remove the screw hold the power light

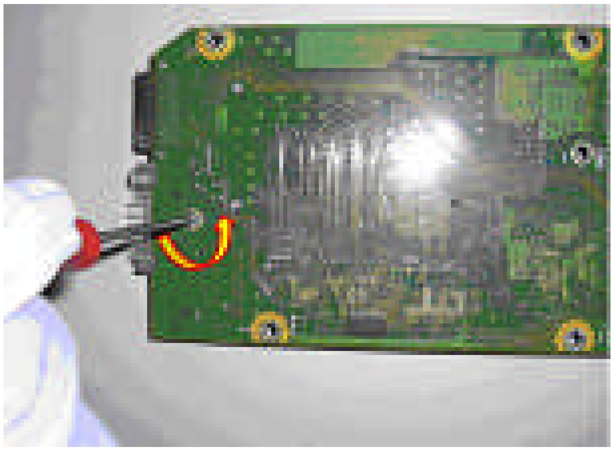


Figure 13 Open the button of the power supply

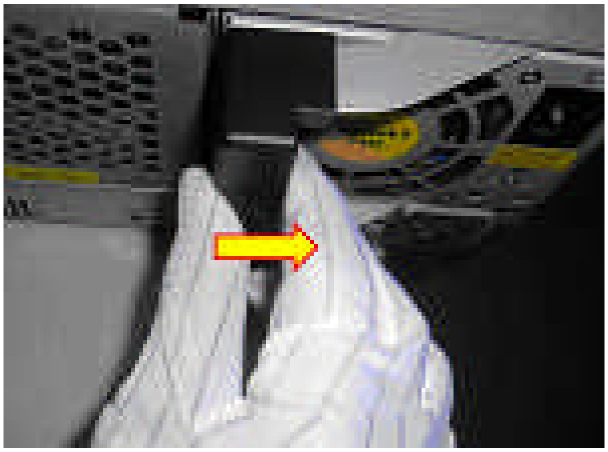


Figure 14 Pull out the power supply from the unit

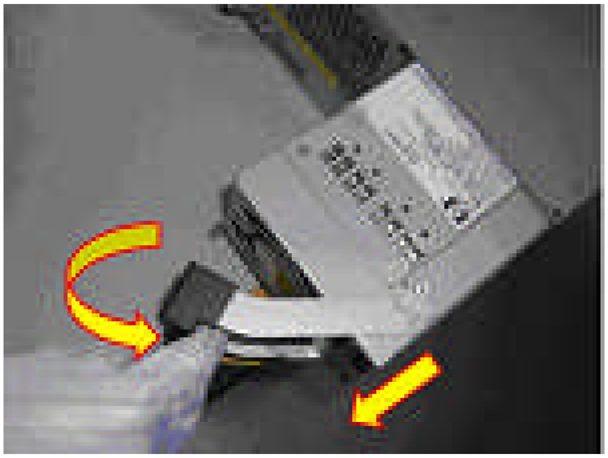


Figure 15 Remove the side screws of the PSU

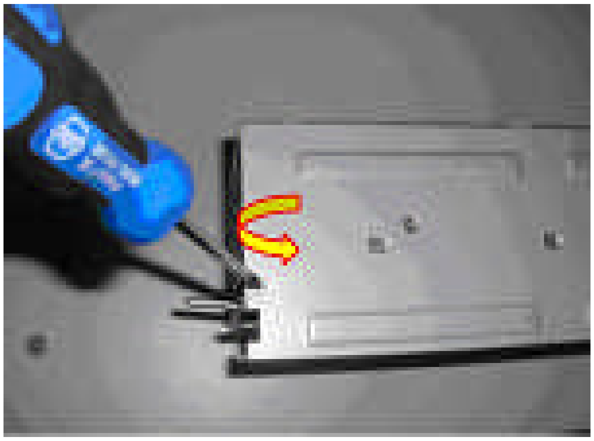


Figure 16 Open the side enclosure of the PSU

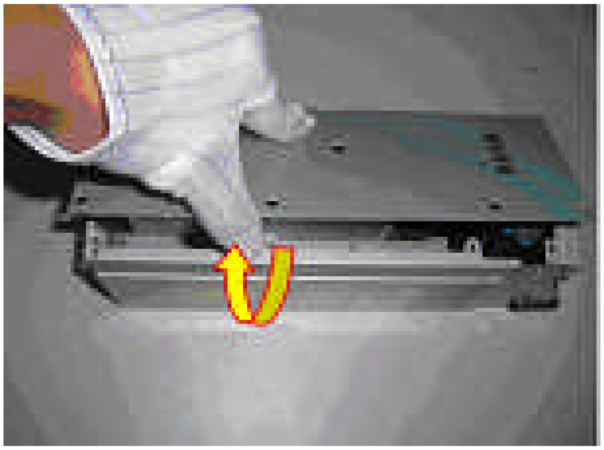


Figure 17 Remove the top screws of the PSU

Figure 18 Open the top enclosure of the PSU

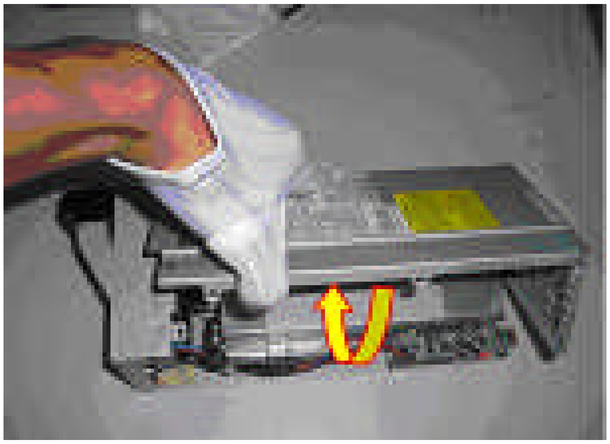


Figure 19 Remove the holding metal for the inside PSU

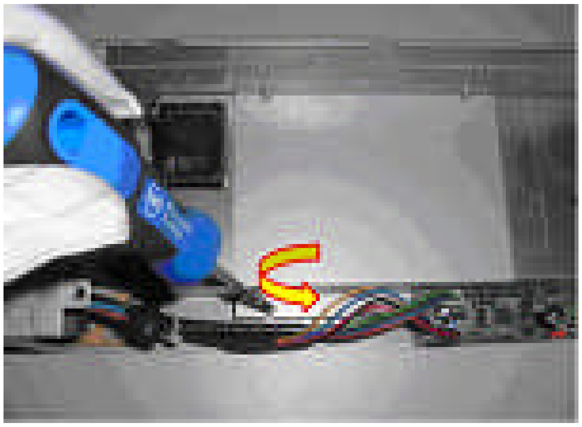


Figure 20 Remove the screws of the inside PSU

Figure 21 Open the power supply

Figure 22 Remove the screws of the PAC of PSU

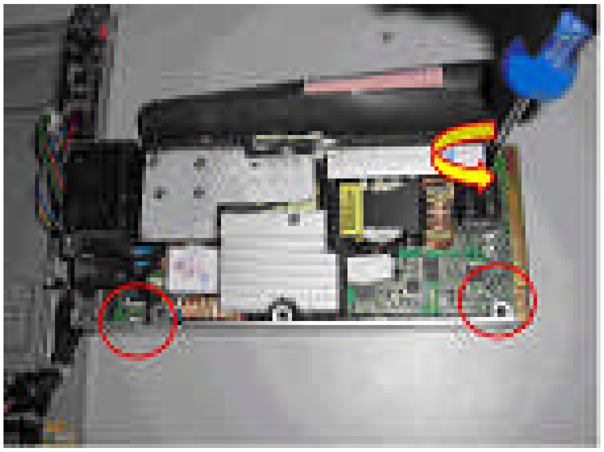


Figure 23 Remove the fan

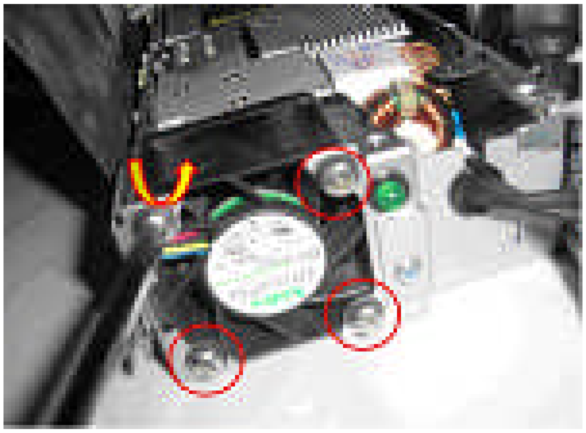


Figure 24 Electrolytic Capacitors location

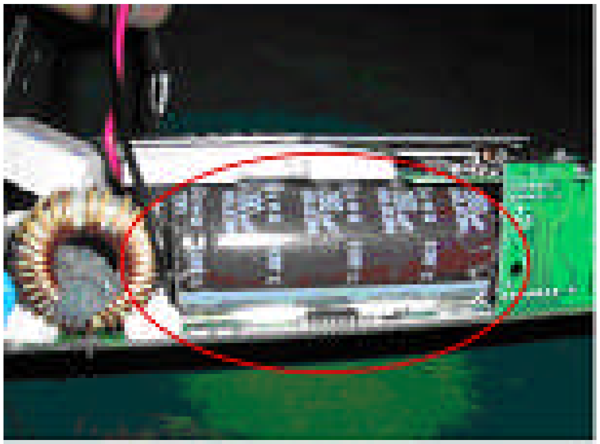


Figure 25 Heat the solder of Electrolytic Capacitors

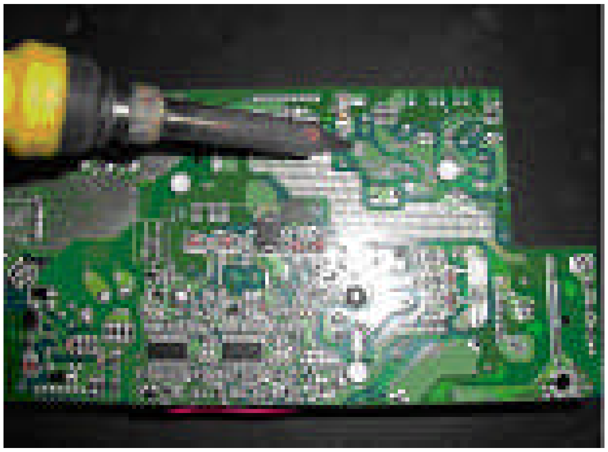


Figure 26 Open the top enclosure

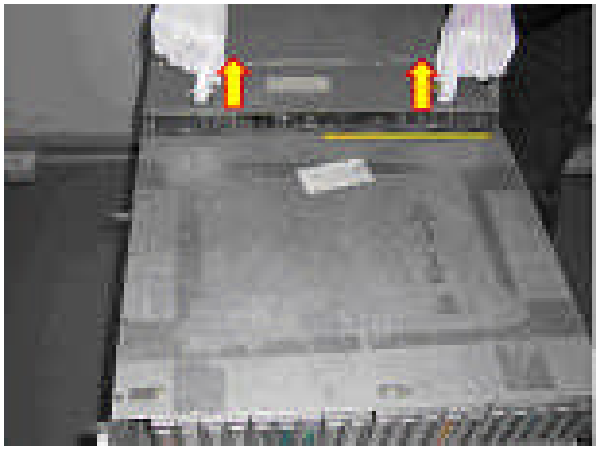


Figure 27 Pull the handle in the two side slot of the PSU

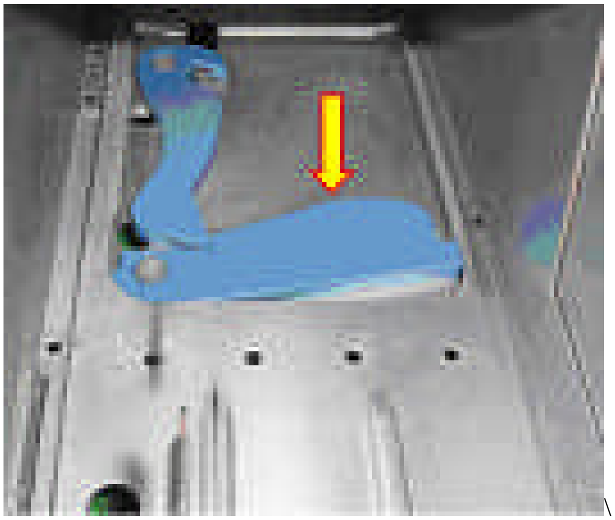


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Figure 28 Use two hands to pull out the backplane

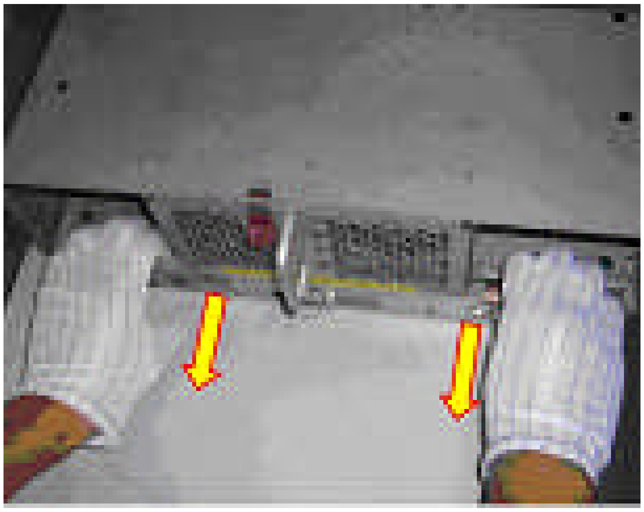


Figure 29 Remove the screws of the top PCA on the backplane

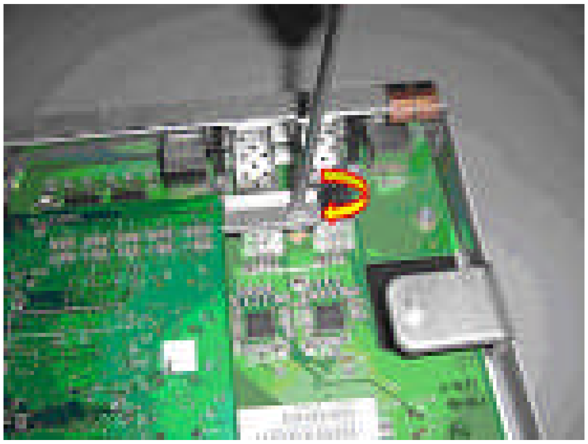


Figure 30 Remove the buttons on the top PCA

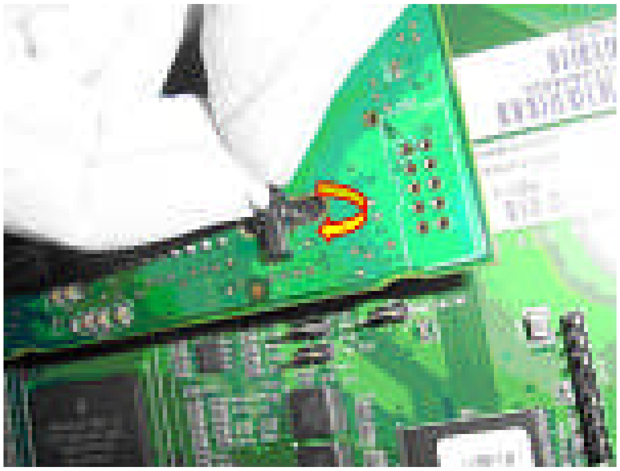


Figure 31 Remove the screws on the VGA connecter

Figure 32 Remove the screws on the backplane PCA

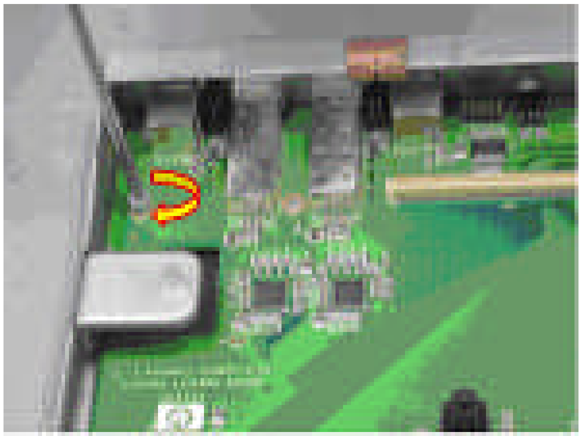


Figure 33 Push out the backplane PCA

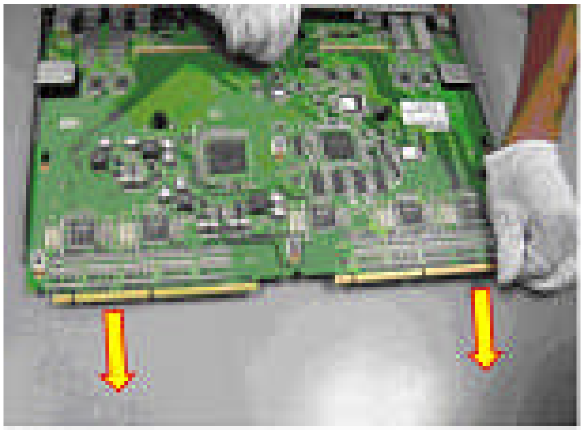


Figure 34 Cut off the fan connector

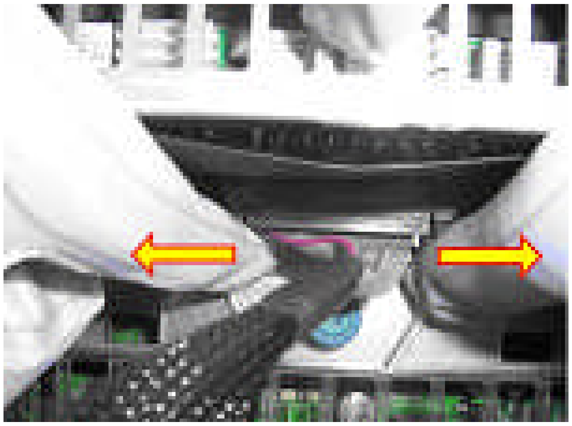


Figure 35 Push down the button at the back of unit

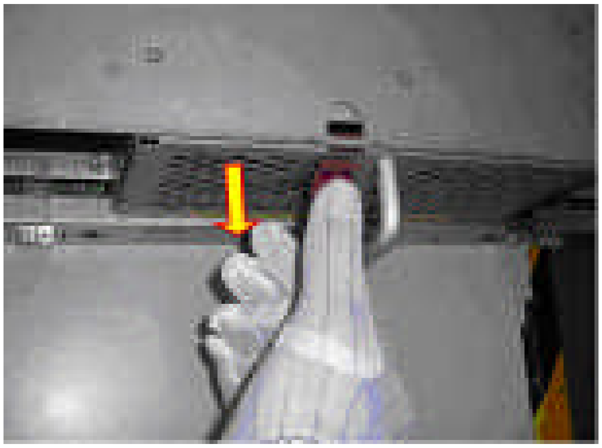


Figure 36 Pull out the Fan controller from the unit

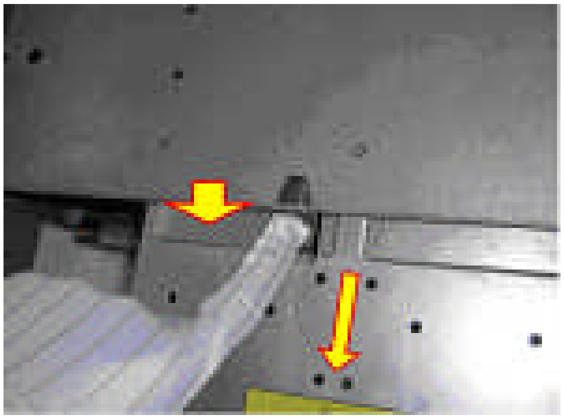
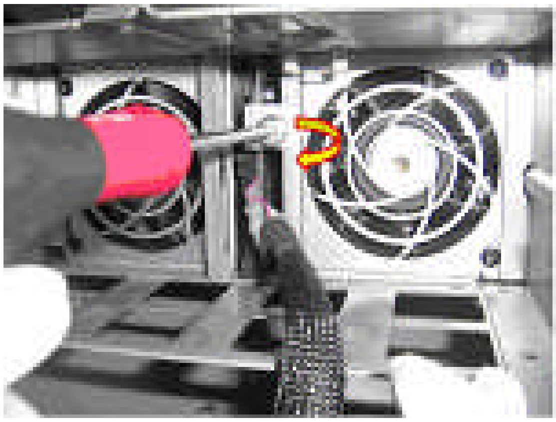
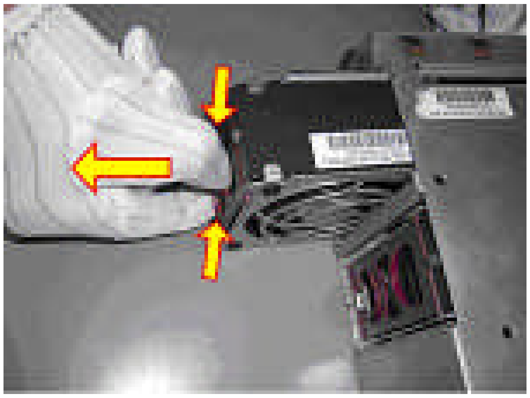
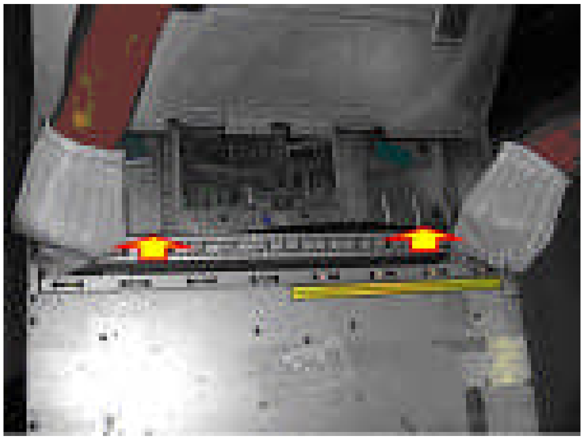
Figure 37 Push down the second button and pull out the fan controller from the unit 	Figure 38 Remove the screw inside the fan cotroller 
Figure 39 Push the handles to the centre and then pull out the four fan 	Figure 40 Remove two side screws of the midplane 
Figure 41 Pull out the midplane 	Figure 42 Remove the screws on the two side of the midplane 

Figure 43 Remove the screws on the two side of the midplane